

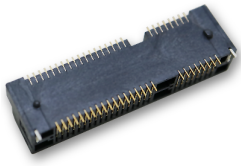
Operation: 0.80MM PITCH MINI-PCI EXPRESS / [MINI-PCI E 连接器]

**REACH**

**RoHS Compliant**

LTEM NO.: PCIE-52P□□H

(L29.9mm × W8.2mm / 52 CIRCUITS WITH FITTING NAILS)



### Technical parameter

PROJECT	LEVEL	A [better product]	
	Contact Rating	0.5A Per PIN / 50V DC	
Electrical Properties	Initial Contact Resistance	50mΩ min.	50mΩ max.
	Insulation Resistance	500MΩ min.	
Durable Performance	Withstand Voltage	300V AC for 1 minute	300 V AC for 1 minut
	There No Load	200 Cycle	
	Rated Load	100 Cycle	
	Storage temp.	-40℃~+85℃ (Operating Temp: )	

表面贴装 SMT

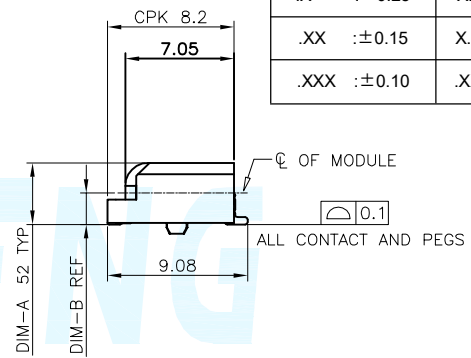
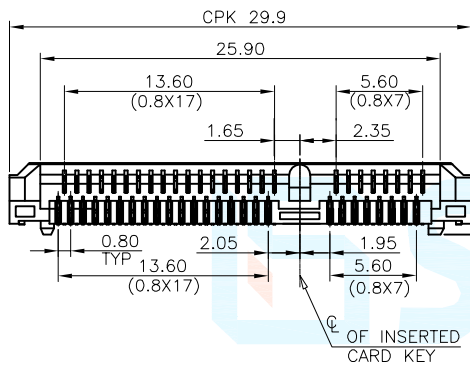
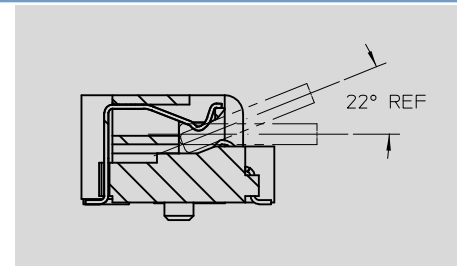
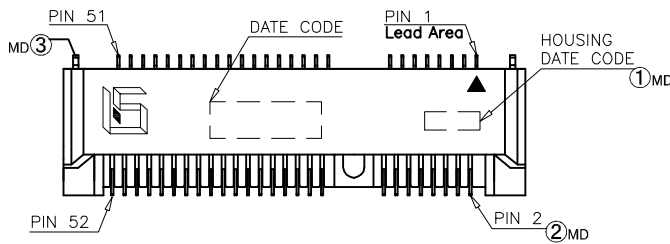
側向導入 LATERAL

精密部品 NICETY

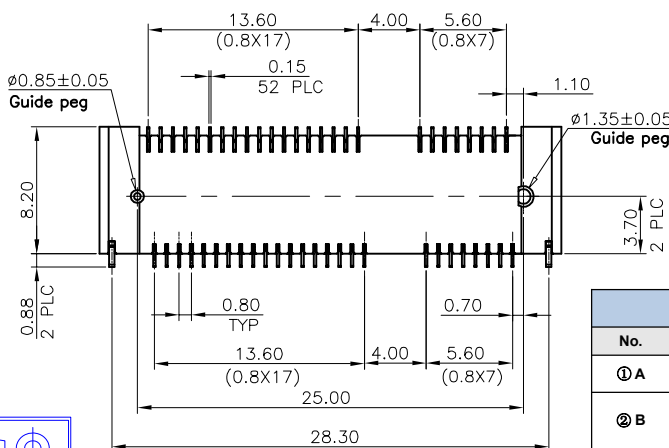
可靠 STABILIZE

適合環保 RoHS

Unit:mm



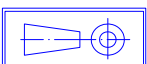
DECIMALS	ANGLES
.X : ±0.25	X.° : ±1.5°
.XX : ±0.15	XX.° : ±1.0°
.XXX : ±0.10	XXX.° : ±0.5°



LTEM NO	DIM A	DIM B
PCIE-52P40H	4.0mm	2.05
PCIE-52P52H	5.2mm	3.25
PCIE-52P56H	5.6mm	3.65
PCIE-52P70H	7.0mm	5.05
PCIE-52P80H	8.0mm	6.05

### Material declaration

No.	NAME	MATERIAL	DESCRIPTION
① A	HOUSING 基座	THERMOPLASTIC LCP MG305	UL 94V-0, COLOR: BLACK;
② B	TERMINAL 接触端子	COPPER ALLOY 【G/F】 磷铜合金 C5210	2.0 μm Ni PLATED OVERALL; 0.25 μm Au PLATED CONTACT AREA; GOLD FLASH ON SOLDER AREA.
③ C	HOLDDOWN 固定端子	COPPER ALLOY 黄铜 C2680	0.25 μm Ni PLATED OVERALL;



Operating Force

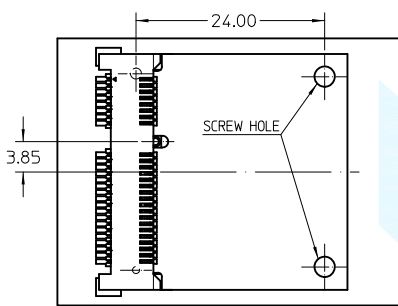
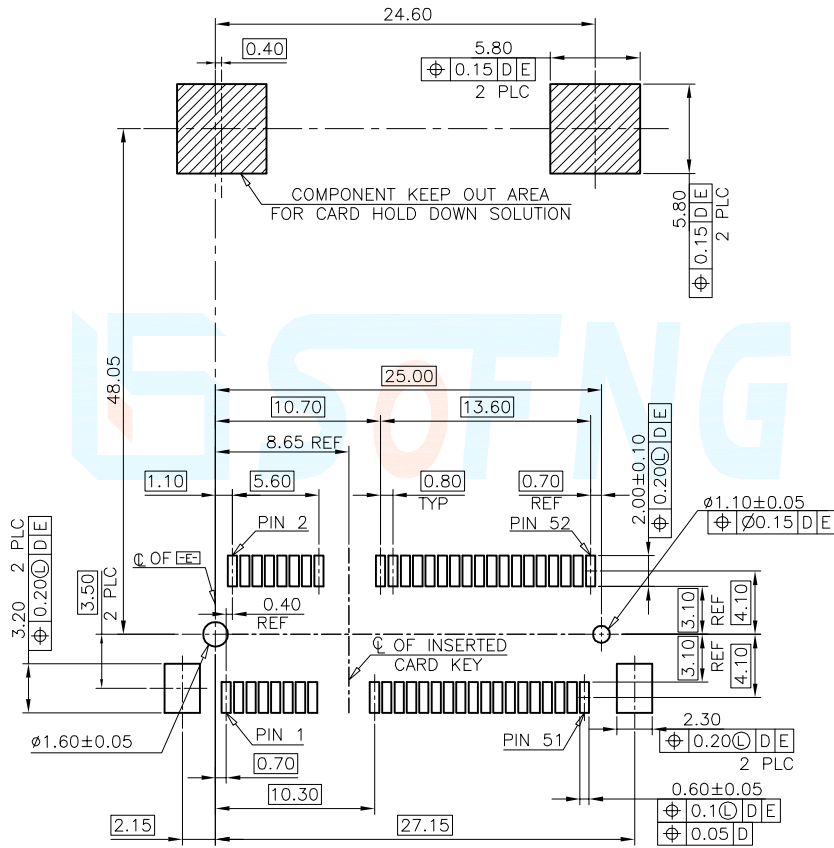
Inward  
Exiting

2.3Kgf MAX.  
2.3Kgf MAX.

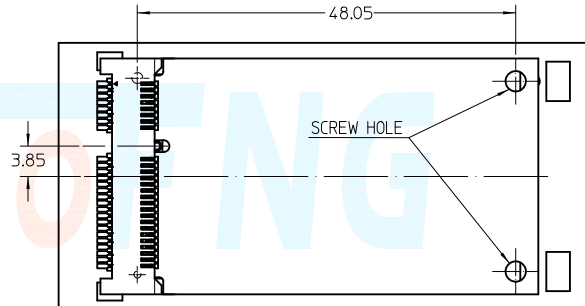
Solder-ability (Max.)

IR Reflow: 255°C, 5sec.

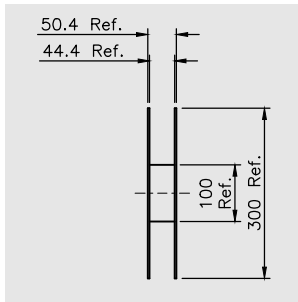
Manual: 350°C, 3sec.



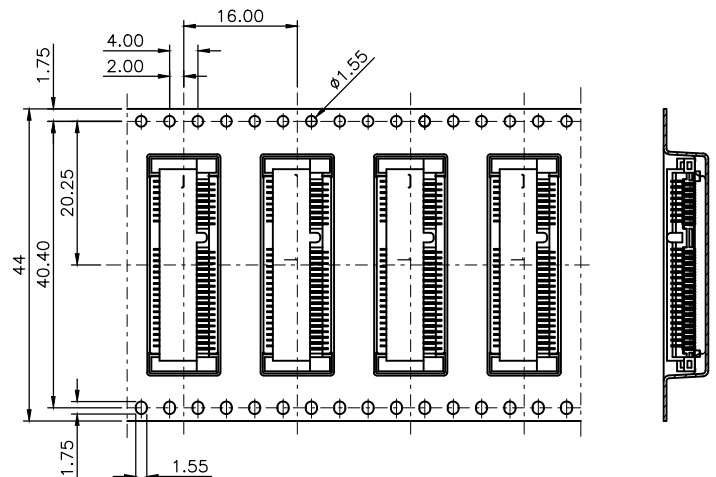
HALF-MINI CARD APPLICATION SCHEMATICS



FULL-MINI CARD APPLICATION SCHEMATICS



PACKING TABLE	
P/N	Q'TY/REEL
PCIE-52P40H	650PCS
PCIE-52P52H	550PCS
PCIE-52P56H	500PCS
PCIE-52P70H	400PCS
PCIE-52P80H	400PCS



注記 NOTICE

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